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Product Change Notification - JAON-03FXZH882

Date: 05 Aug 2016
Product Category: Analog (Thermal, Power Management & Safety)
Notification subject: CCB 2720 Initial Notice: Qualification of QMI529HT-LV die attach material for selected Micrel products available in 20L SOIC package at UNIB assembly site.
Notification text: **PCN Status:**
 Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of QMI529HT-LV die attach material for selected Micrel products available in 20L SOIC package at UNIB assembly site.

Pre Change:

Using 2600AT die attach material.

Post Change:

Using QMI529HT-LV die attach material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	UNIB assembly site	UNIB assembly site
Wire material	Au wire	Au wire
Die attach material	2600AT	QMI529HT-LV
Molding compound material	G600	G600
Lead frame material	CU194	CU194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To Improve On-Time Delivery Performance by qualifying QMI529HT-LV die attach material. The 2600AT die attach material will no longer be available for use to assemble selected Micrel products in 20L SOIC package at UNIB assembly site.

Change Implementation Status:

In Progress

**Estimated Qualification Completion Date:
October 2016**

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

Workweek	August 2016				->	October 2016			
	31	32	33	34		40	41	42	43
Initial PCN Issue Date	X								
Qual Report Availability						X			
Final PCN Issue Date						X			

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
August 5, 2016: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-03FXZH882_Qual_Plan.pdf](#)
 - [PCN_JAON-03FXZH882_Affected_CPN.pdf](#)
 - [PCN_JAON-03FXZH882_Affected_CPN.xlsx](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-03FXZH882
CATALOG_PART_NBR
MIC2177-3.3YWM
MIC2177-3.3YWM-TR
MIC2177-5.0YWM
MIC2177-5.0YWM-TR
MIC2177YWM
MIC2177YWM-TR
MIC2178-3.3YWM
MIC2178-3.3YWM-TR
MIC2178-5.0YWM
MIC2178-5.0YWM-TR
MIC2178YWM
MIC2178YWM-TR